

-2-

ONS00149
09/817,330

IN THE TITLE

Please amend the title as follows.

METHOD OF MAKING A LEAD-FREE INTEGRATED CIRCUIT PACKAGE
~~AND METHOD~~

CLAIM OBJECTION

Claims 19-31 are objected to on the basis that "first surface" in claim 19 should be "second surface" and "second surface" in claim 20 should be "first surface". Claims 19-25 and 29 are modified as shown below to incorporate the language preferred by the examiner.

-2-